



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-08-14
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement	
Supplier Acceptance *	Legal Declaration *
true	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMA6J33A-TR	8HSR*TWU039D	A	ZA41	2018-08-14
	Amount	UoM	Unit type	ST ECOPACK Grade
	70.00	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	250	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.3 x 2.77 x 2	2	J bend	
Comment	Package: SMA			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

California 65 list			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	143
Lead	2.60	Soft solder	37143

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.60	Soft solder	37143
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.60	Soft solder	924609

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8HSR*TWU039D					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.661	mg	supplier	die	Silicon (Si)	7440-21-3		1.573	mg	947020	22471
				supplier	metallization	Aluminium (Al)	7429-90-5		0.061	mg	36725	871
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	5418	129
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.006	mg	3613	86
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1204	29
Leadframe	Copper and its alloy	26.543	mg	supplier	alloy	Nickel (Ni)	7440-02-0		0.010	mg	6020	143
				supplier	alloy	Copper (Cu)	7440-50-8		26.530	mg	999510	379000
				supplier	alloy	Zinc (Zn)	7440-66-6		0.001	mg	38	14
				supplier	alloy	Iron (Fe)	7439-89-6		0.003	mg	113	43
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	339	129
Soft solder	Solder	2.812	mg	supplier	solder	Silver (Ag)	7440-22-4		0.071	mg	25249	1014
				supplier	solder	Tin (Sn)	7440-31-5		0.141	mg	50142	2014
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.600	mg	924609	37143
Encapsulation	Other inorganic materials	38.352	mg	supplier	mold compound	Amorphous Silica	7631-86-9		23.633	mg	616213	337614
				supplier	mold compound	Quartz	14808-60-7		7.670	mg	199990	109571
				supplier	mold compound	epoxy resin	25068-38-6		4.602	mg	119994	65743
				supplier	mold compound	phenolic resin	9003-35-4		2.301	mg	59997	32871
				supplier	mold compound	Bismuth trioxide	1304-76-3		0.027	mg	703	386
				supplier	mold compound	chlorine residue	7782-50-5		0.004	mg	104	57
Connections coating	Solder	0.632	mg	supplier	mold compound	Carbon black	1333-86-4		0.115	mg	2999	1643
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.632	mg	1000000	9029